


MATERIAL DECLARATION SHEET



Material Number	BSDH08G65E2 TO220-2			
Product Line	Semiconductor			
Compliance Date	2023-05-22			
RoHS Compliant	YES	MSL	N.A.	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Die	Silicon Carbide	1.07	Silicon Carbide (SiC)	409-21-2	100	0.053	0.053
2	Die Attach	Die Attach	0.05	Diethylene Glycol Monoethyl Ether Acetate	112-15-2	5	0.002	0.047
			0.9	Silver (Ag)	7440-22-4	95	0.045	
3	Lead Frame	Copper alloy	0.43	Phosphorous (P)	7723-14-0	0.03	0.021	70.505
			1.42	Iron (Fe)	7439-89-6	0.1	0.071	
			1415.16	Copper (Cu)	7440-50-8	99.87	70.413	
4	Mold Compound	Resin	37.38	Phenol Formaldehyde resin (generic)	9003-35-4	6.5	1.86	28.611
			92	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	16	4.578	
			408.25	Silica fused	60676-86-0	71	20.313	
			37.38	Metal hydroxide	Trade Secret	6.5	1.86	
5	Plating	Tin plating	15	Tin (Sn)	7440-31-5	100	0.746	0.746
6	Wire	Pure metal	0.77	Aluminium (Al)	7429-90-5	100	0.038	0.038
Total weight			2009.81 mg					

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(EU) RoHS Directive 2011/65/EU ANNEX Application of lead which are exempted from the requirements